

- 注記(NOTES)
1. 使用材料 (MATERIAL)  
ターミナル (TERMINAL): リン青銅  
PHOSPHOR BRONZE  $\pm 0.2$   
錫ビスマスマスメリ 1. 0マイクロメートル以上  
TIN-BISMUTH 1.0 MICROMETER MINIMUM  
ニッケル下地 1. 0マイクロメートル以上  
NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM  
ハウジング (HOUSING): 46ナイロン (46NYLON), UL 94V-0  
金具 (FITTING NAIL): リン青銅  
PHOSPHOR BRONZE  $\pm 0.2$   
錫メッキ 1. 0マイクロメートル以上  
TIN 1.0 MICROMETER MINIMUM  
ニッケル下地 1. 0マイクロメートル以上  
NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
  2. パターン剥離止め用金具。(FITTING NAIL FOR PREVENTION OF PEELING OFF PCB. PATTERN.)  
ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 L に対し上方向 0.1MAX. 下方向 0.15MAX. とする。
  3. MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM L  
UPPER DIRECTION 0.1MAX., LOWER DIRECTION 0.15MAX.  
偶数極に適用。(TO BE APPLIED ONLY WHEN ALL CKTS. ARE EVEN.)
  5. 本製品は 52689-\*\*\*40 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE 52689-\*\*\*40.

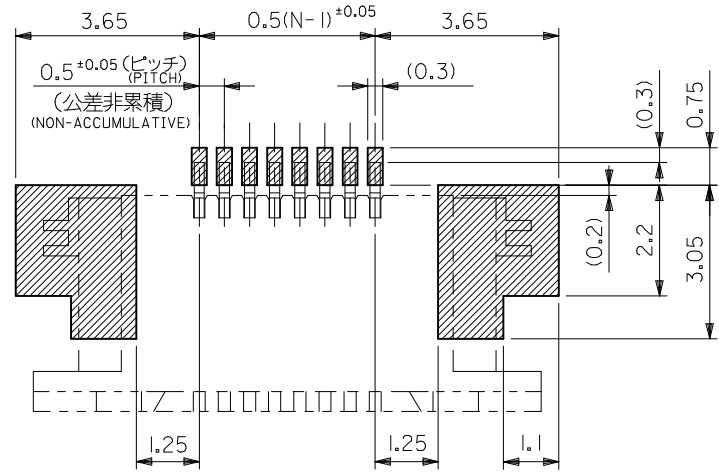
MODEL NO. 52689-\*\*\*49  
DESIGN UNITS METRIC  
THIRD ANGLE PROJECTION

0.5 FPC CONN NON ZIF  
HSG ASSY FOR SMT(R/A)  
-LEAD FREE-

**molex**

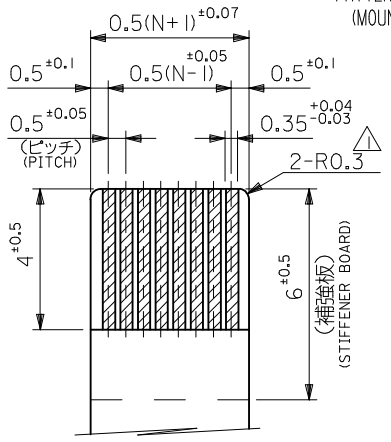
DOCUMENT NO. SD-52689-034  
SHEET NO. 1 OF 2

GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE		SCALE	DESIGN UNITS
0.25 UNDER	UNDER	±	MM ONLY		---	METRIC
0.25 OVER	0.5 UNDER	±	DRAWN BY	DATE	TITLE	
0.5 OVER	1.0 UNDER	±	H. KAWABATA	'04/02/03	0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-	
0 OVER	10 UNDER	±0.2	CHECKED BY	DATE		
10 OVER	30 UNDER	±0.25	K. TOJO	'04/02/03		
30 OVER		±0.3	APPROVED BY	DATE		
ANGULAR	±3 °		M. SASAO	'04/02/03		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			MATERIAL NO.		SEE SHEET 2	
			SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
			A3			

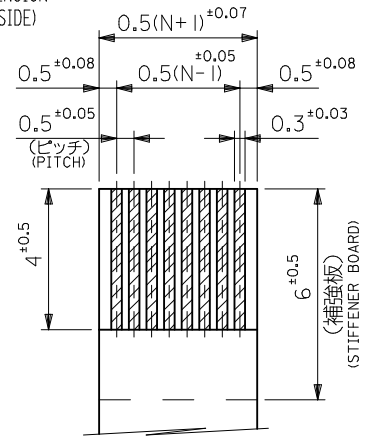


参考基板レイアウト  
(マウント面)

REFERENCE P.C. BOARD  
PATTERN DIMENSION  
(MOUNTING SIDE)



適合FPC推奨寸法  
APPLICABLE FPC  
RECOMMENDED DIMENSION  
(仕上がり厚さ: 0.3±0.03)  
(THICKNESS: 0.3±0.03)



適合FFC推奨寸法  
APPLICABLE FFC  
RECOMMENDED DIMENSION  
(仕上がり厚さ: 0.3±0.03)  
(THICKNESS: 0.3±0.03)

FPCについて:  
打抜き方向は導体側から補強板側を推奨致します。  
補強フィルム材質はポリイミドを推奨致します。  
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:  
RECOMMENDED PUNCHER DIRECTION : FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.  
RECOMMENDED MATERIAL :  
STIFFENER FILM : POLYIMIDE  
BONDING AGENT : THERMOSETTING BONDING AGENT

注記 NOTES

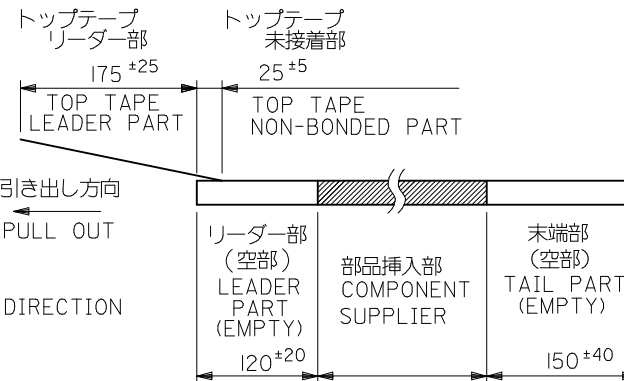
△ R0.3は、FPCの導体部にかからないこと。  
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

52689-***49	17.6	21.1	19.3	15.5	14.5	52689-3087	52689-3049	30
MODEL NO.	W	D	C	B	A	EMBOSSED TAPE	MATERIAL NO.	極数 CKT.
	13.6	17.1	15.3	11.5	10.5	ORDER No. オーダー番号	52689-2287	52689-2249

REVISED EC NO: J2017-0300 DRAWINGS CHKD: APPR: MSASAO	DESCRIPTION 2016/12/01 2016/12/20	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		0.25 UNDER UNDER ±	0.25 OVER 0.5 UNDER ±	DRAWN BY H. KAWABATA	DATE '04/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-			
		0.5 OVER 1.0 UNDER ±	0 OVER 10 UNDER ±0.2	CHECKED BY K. TOJO	DATE '04/02/03				
		10 OVER 30 UNDER ±0.25	30 OVER ±0.3	APPROVED BY M. SASAO	DATE '04/02/03				
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

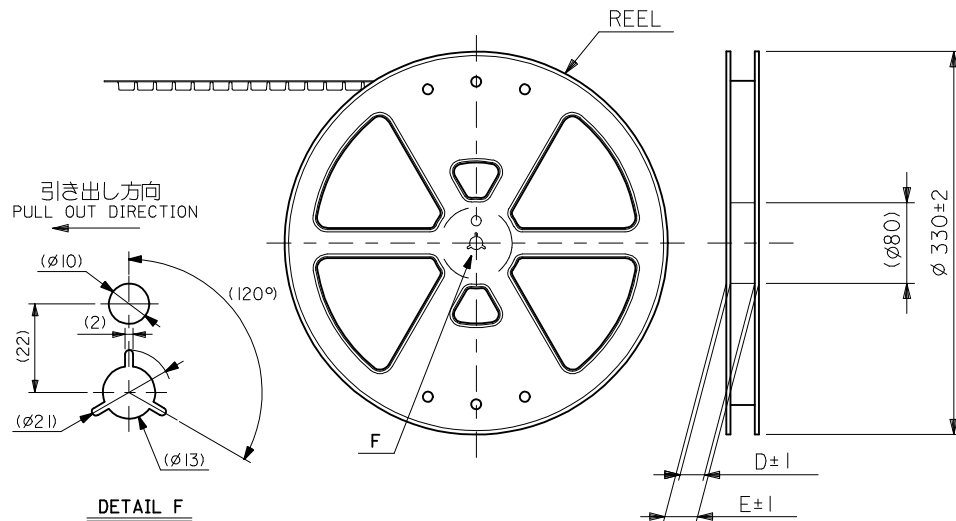
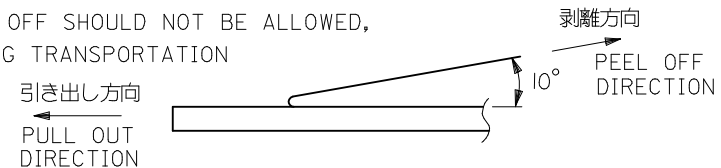
注記 NOTES

- 製品詳細寸法については図面 SD-52689-034 を参照下さい。  
RE DETAILED DIMENSION,SEE SD-52689-034.
- 梱包数量：1000個/リール  
NUMBER OF CONNECTORS:1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- トップテープの剥離強度：(剥離方向は下図参照)  
0.1~1.3N {10~130gf}  
尚、本規格値は、出荷時に適用。(但し、輸送時に剥離が発生しない事。)

PEELING OFF FORCE OF TOP TAPE  
0.1~1.3N {10~130gf} (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)  
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT  
PEEL OFF SHOULD NOT BE ALLOWED,  
DURING TRANSPORTATION



- 材料  
キャリアテープ：ポリプロピレン (PP)  
トップテープ：PET, PE, PEF  
リール：ポリスチレン (PS) <リサイクル材を含む>

MATERIAL CARRIER TAPE:POLYPROPYLENE  
TOP TAPE:PET,PE,PEF  
REEL:POLYSTYREN(PS)  
<RECYCLE MATERIAL CONTAINED>

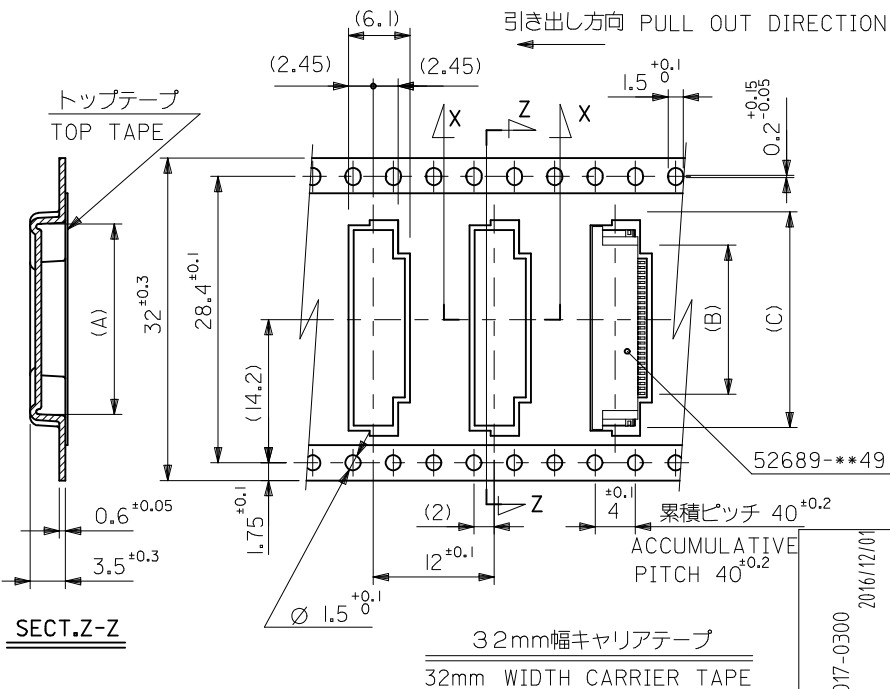
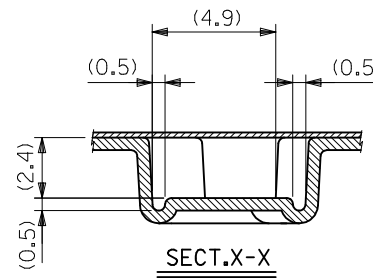
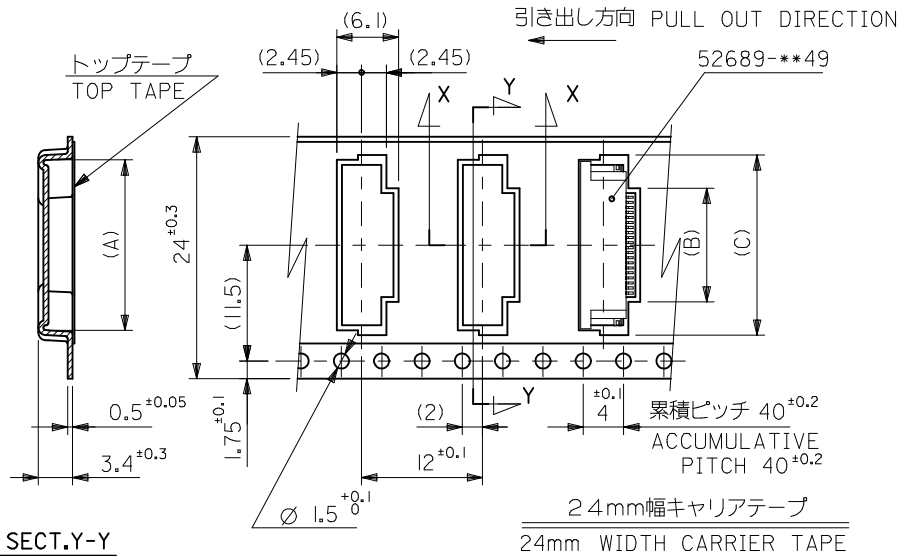
- 本製品は52689-\*\*\*93の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 52689-\*\*\*93.

- FPCについて：  
打抜き方向は導体側から補強板側を推奨致します。  
補強フォルム材質はポリイミドを推奨致します。  
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:  
RECOMMENDED PUNCHER DIRECTION :  
FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.  
RECOMMENDED MATERIAL :  
STIFFENER FILM : POLYIMIDE  
BONDING AGENT : THERMOSETTING BONDING AGENT

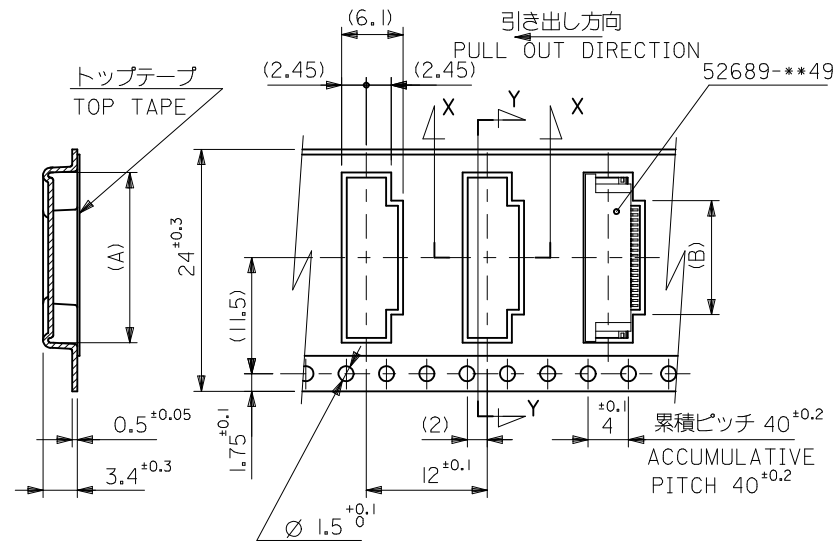
- 本製品は乾燥剤入り、ハイバリア梱包仕様である。  
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

REVISED EC NO: J2017-0300 DRAWINGS CHKD: APPR:MSASAO	DESCRIPTION 2016/12/01 2016/12/20	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		0.25 UNDER	UNDER	±0.03	DRAWN BY H.KAWABATA	DATE 2004/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-	DOCUMENT NO. SD-52689-035	SHEET NO. 1 OF 3
0.25 OVER	0.5 UNDER	±0.05	CHECKED BY K.TOJO	DATE 2004/02/03	MATERIAL NO. SEE SHEET 2,3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
0.5 OVER	1.0 UNDER	±0.1	APPROVED BY M.SASAO	DATE 2004/02/03					
1.0 OVER	10 UNDER	±0.2							
10 OVER	30 UNDER	±0.25							
30 OVER		±0.3							
		ANGULAR	±3						
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3					



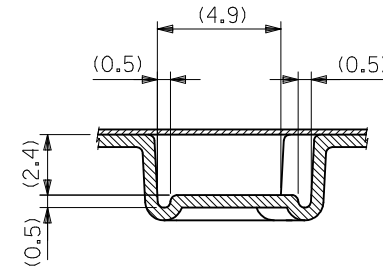
52689-**-87	32	37.4	33.4	22.4	15.8	21.4	52689-3087	30
MODEL NO.	キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MATERIAL NO.	種数 CIRCUIT

REVISED EC NO: J2017-0300 DRAWINGS CHKD: APPR:MSASAO	2016/12/01	2016/12/20	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	DESCRIPTION	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
		0.25 OVER	0.5 UNDER	±0.05	H.KAWABATA	2004/02/03	0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-		
		0.5 OVER	1.0 UNDER	±0.1	K.TOJO	2004/02/03	molex		
	1.0 OVER	10 UNDER	±0.2	APPROVED BY	DATE	DOCUMENT NO.			
	10 OVER	30 UNDER	±0.25	M.SASAO	2004/02/03	SD-52689-035			
	30 OVER		±0.3	MATERIAL NO.		SHEET NO.			
	ANGULAR	±		SEE TABLE		2 OF 3			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



SECT.Y-Y

24mm幅キャリアテープ  
24mm WIDTH CARRIER TAPE



SECT.X-X

24	29.4	25.4	11.8	17.4	52689-2287	22
52689-***87	キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(B)	(A)	MATERIAL NO. 極数 CIRCUIT

REVISED EC NO: J2017-0300 DRAWN: 2016/12/14 CHKD: APPR: MSASAO	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	±0.05	H. KAWABATA	2004/02/03	0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-		
	0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE	molex		
1.0 OVER	10 UNDER	±0.2	K. TOJO	2004/02/03	DOCUMENT NO.			
10 OVER	30 UNDER	±0.25	APPROVED BY	DATE	SD-52689-035		3 OF 3	
30 OVER		±0.3	M. SASAO	2004/02/03	SEE TABLE			
ANGULAR	±3		MATERIAL NO.		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3					